



UNIUNEA EUROPEANĂ



GUVERNUL ROMÂNIEI

Programul Operațional Sectorial
"Creșterea Competitivității Economice"
"Investiții pentru viitorul dumneavoastră"



INSTRUMENTE STRUCTURALE
2007-2013

POS CCE: 665/12609/209/20.07.2010

Wafer-Substrate Bonder System

Suss MicroTec SB6L

MICRONANOFAB

GENERAL CHARACTERISTICS:

- ✓ Lower hot bond chuck with temperature control from ambient to 500°C
- ✓ Negative High Voltage DC power supply for Anodic bonding
- ✓ Flexible process: can accommodate polymer and adhesive bonding of different substrates

APPLICATIONS

- ✓ Bonding processes:
 - Silicon to silicon
 - Silicon to glass
 - Pressure/heat assisted polymer bonding
 - Adhesive/pressure/heat assisted bonding

PERFORMANCE:

- ✓ temperature control $\pm 3^{\circ}\text{C}$
- ✓ temperature uniformity $\pm 2\%$
- ✓ up to 8kN applied force
- ✓ process vacuum pressure down to $5 \cdot 10^{-4}$ mbar



ADVANTAGES:

- ✓ Strong durable bonds
- ✓ Excellent for encapsulation
- ✓ Excellent for enclosure of fluidic microchannels
- ✓ User friendly recipe editor for non-standard processes

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